









Flexible Manufacturing Tool

The proven CT_2 delivers remarkable flexibility and dependable output in one fully functional assembly cell. CT_2 offers reliable positional accuracy and speed through advanced linear motion and vision technology. Configured as a standalone instrument or integrated with your production line, CT_2 is the ideal choice for process development, line validation and a wide range of semi-conductors, electronics and medical device assembly applications.

Flexible Upgradable

 CT_2 provides industry-leading flexibility in a pick/place platform. Dual heads and a full complement of upward- and downward-looking cameras provide a base for multiple machine configurations while extensive material handling capability allows conveyors, feeding systems, dispensing modules and process tooling. Easily adapted and reconfigured to meet the specific requirements of new production challenges, the CT_2 provides excellent investment protection through a wide range of upgrade options.

Reliable Quality

For demanding semiconductor packaging and module assembly processes, the CT_2 has a proven, reliable track record as a manufacturing workhorse. Combining linear motors, low part count and a simple machine design minimizes performance loss and assures lont-term uptime. Quality and safety features meet or exceed Semiconductor Equipment and Materials International's (SEMI) Safety Guidelines as well as CE marking requirements.

Capable Customizable

Combining a linear motion gantry with an industry proven controller and amplification system enable the configuration of motion speed, acceleration and direction for all axes. Maintaining speed along with the ability to customize new system settings is accomplished through programmable move paths and user-definable process steps.



Preform and Heatsink
Placement Fiber Optic
Lens/Lid Assembly
Epoxy/Flux Dispensing
Substrate I/O Inspection
Biochip Development
Substrate Ball Attach
Lid/Clip Placement MEMS
Assembly MCM Assembly
Die Placement Flip Chip

CT2 Specifications

Transfer/Placement Heads

Placement pressure range 0.22lbs (0.1 kg) to

4.4lbs (2.0 kg)

Spring loaded compliant tips are used for lower force

requirements

Programmable Z-speed, pressure and dwell time

Options Optional end-of-arm tooling equipment

LaserAlign optical in-flight alignment of components

up to 32mm (1.26")

Vacuum nozzles, die collets, custom tools

Tray/Process Carriers/Substrate Handling

Dimensions (x, y) 3" x 2 (75mm x 51mm) up to

18" x 20" (457mm x 508mm)

Subject to process configuration

Types Auer, JEDEC (or similar design), BGA, graphite boats,

custom carriers, lead frames, strips, PWBs, clipping, and

custom part securing

Bi-directional conveyors (single or dual)

Components

Dimensions Minimum:0.01" x 0.01" (0.25mm x 0.25mm)

from waffle pack,

0.04" x 0.04" (1.02mm x 1.02mm)

from wafer

Maximum: 3" x 3" (75mm x75mm)

Consult factory for specific size and weight >1 kg

Performance

Placement Accuracy X, Y 0.001" (0.025mm)

Z Normally compliant

All values are 3 sigma values using local fiducial vision tools

Encoder Resolution X, Y 0.000008" (0.002mm)

Z 0.000004" (0.0010mm)

Theta 0.005 degrees

Placement Rate 800 - 2000 UPH (subject to process)

Standard Component Handling and Feeding Systems

Pallet stacker/destacker Wafer die ejector

Tray feeders (waffle pak, gel pak, custom)

Label feeders Static platforms

Tape and reel feederbanks

Options

Auto vacuum tip change rack Barcode reader and writer Custom under-board support Epoxy and adhesive dispense heads

Flux applicators

Dimensions and Weight

Weight

Footprint 41.3" W x 45.5" D x 65.0" H (1.04m x 1.16m x 1.65m) Work Envelope (x, y, z) 22" x 26" x 3.5" (559mm x 660mm x 89mm)

Subject to process configuration 2500 lbs (1134 kg)

For more information: Contact us at 1-919-212-1279 or visit our website at www.arconparts.com